



(1.00 mm) .0394"

POLARIZED MICRO HEADER & SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BKT or www.samtec.com?BKS

Insulator Material:
Liquid Crystal Polymer
Terminal Material:
Phosphor Bronze
Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating:
2.8 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(1.40 mm) .055" minimum
Normal Force:
40 grams (0.39 N) average
Max Cycles:
100 with 10 µ" (0.25 µm) Au
RoHS Compliant:

PROCESSING

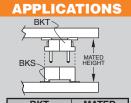
Lead-Free Solderable: Yes SMT Lead Coplanarity: (0.10 mm) .004" max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



PLATING NO. OF **BODY** BKT **OPTIONS POSITIONS OPTION STYLE** Mates with: Specify –S BODY = Shrouded STYLE (15 positions 07 thru 69 = Gold flash on post, minimum) from (Odd lead counts only) Matte Tin on tail chart $-\mathsf{A}$ = Alignment --+---+ (5.08) = 10 μ" (0.25 μm) Gold on post Pin BOARD (2.54) (5.59) .100 .220 BODY STYLE Matte Tin on tail (Metal or SPACE (Mated with BKS) plastic at 0 0 + + 0 0 0 + Samtec (1.93)(3.91)**←** 01 -01 (4.14).163discretion) .076 .154 (13 positions ← (0.50) .020 TYP (2.29)(4.27) -02(4.50).177minimum) .090 .168 _ _ _ _ _ _ _ _ _ ► (0.31) .012 SQ TYP (2.79)(4.78)(1.65) -03(5.00).197(6.35) .250 110 .188 = Pick & (5.77) .227 (3.78)0 0 0 0 -04 (6.00).236Place Pad ____A .149 (13 positions (4.80)(6.78)(0.50) .0197 x ← (No. of positions +1) → + (0.25) .010 (7.00).276(0.50) .0197 x minimum) 189 267 (No. of positions +1) + (2.44) .096 (4.17 x 5.71) .164 x .225 -TR -S OPTION = Tape & Reel Packaging (0.20) (3.61) В (0.89) -.035 DIA -P OPTION -A OPTION



BKT	MATED
LEAD STYLE	HEIGHT*
-01	(4.14) .163
-02	(4.50) .177
-03	(5.00) .197
-04	(6.00) .236
-05	(7.00) .276
*Processing conditions will	



Note:

Some sizes, styles and options are non-standard, non-returnable.

